

FIG. 1

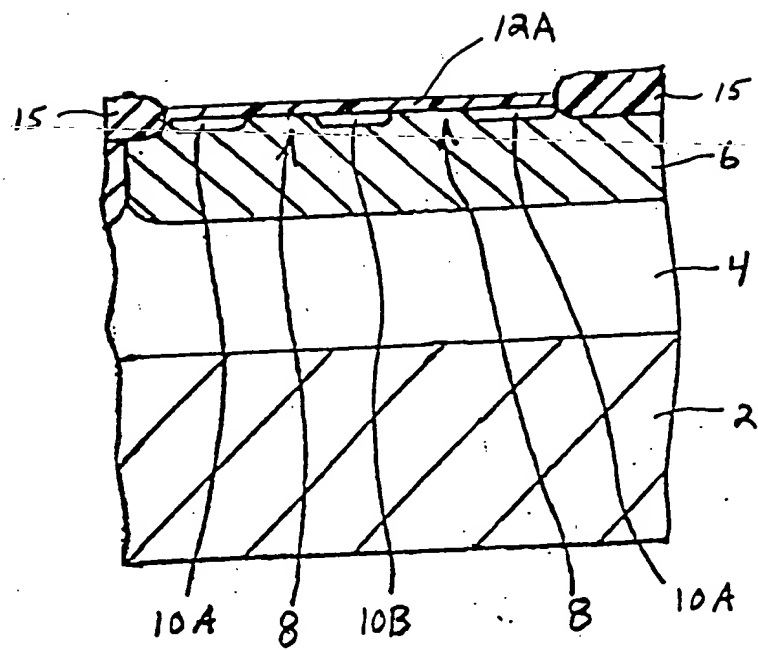


FIG. 2

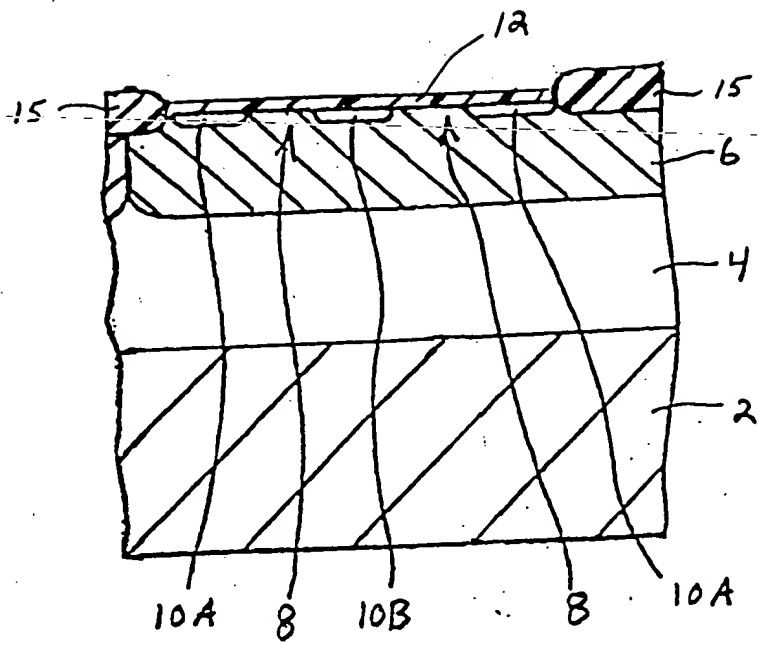


FIG. 3

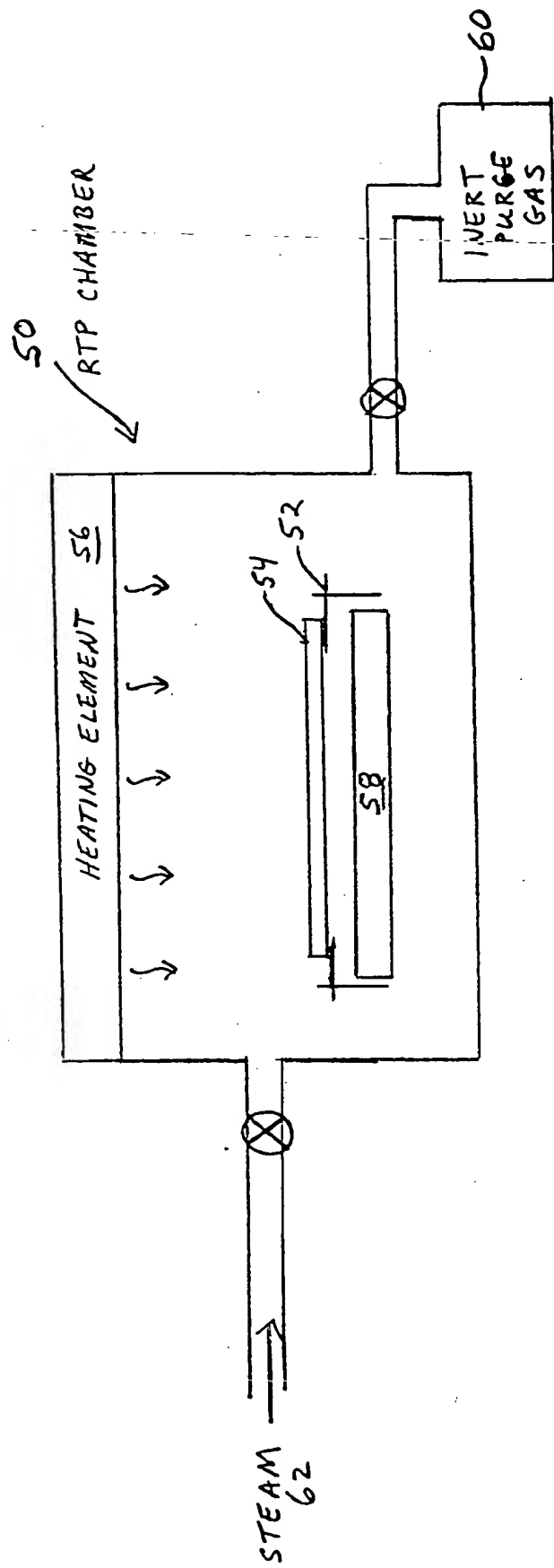


FIG. 4

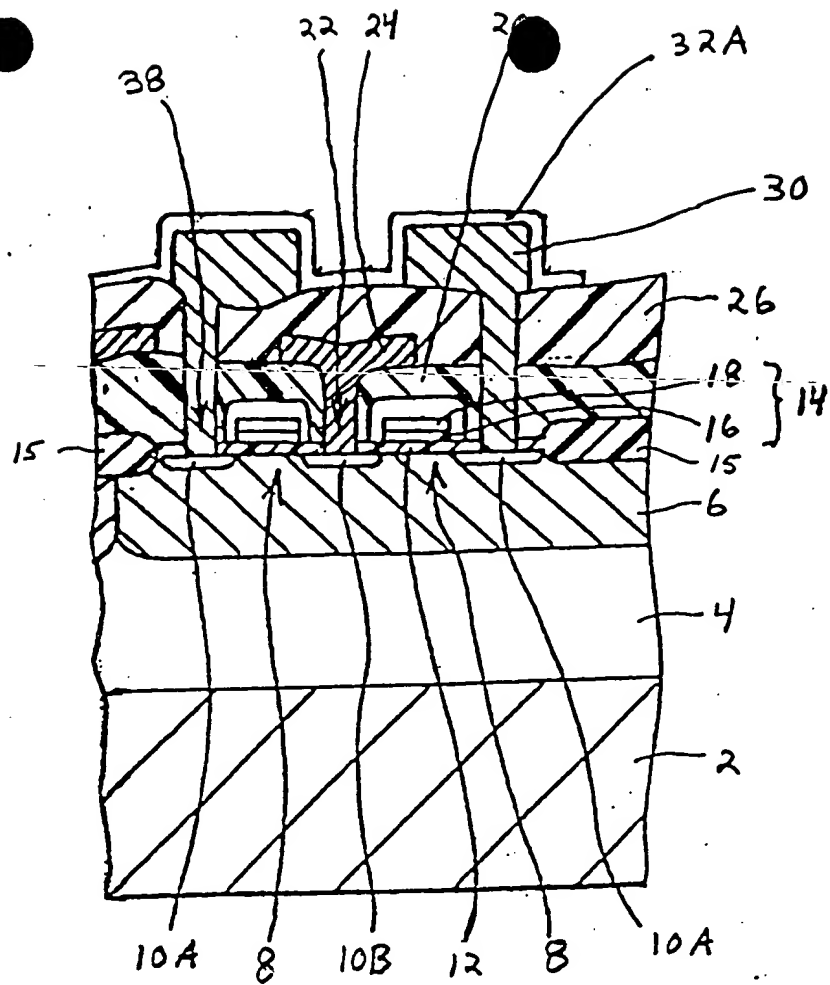


FIG. 5

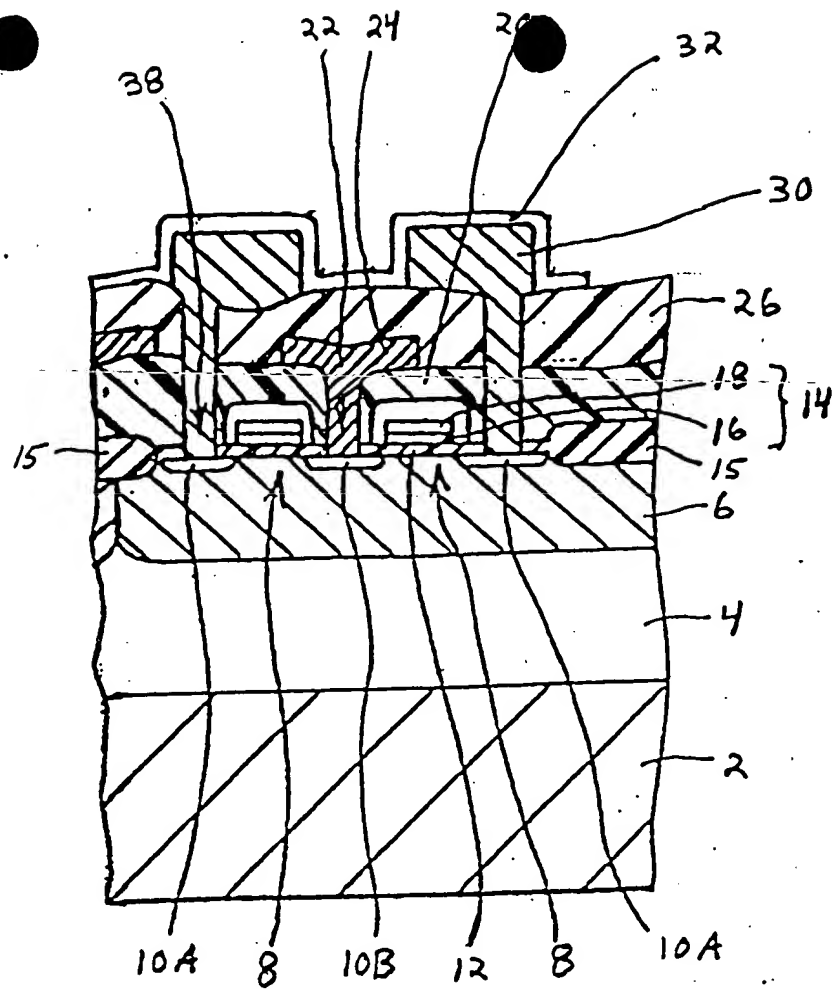


FIG. 6

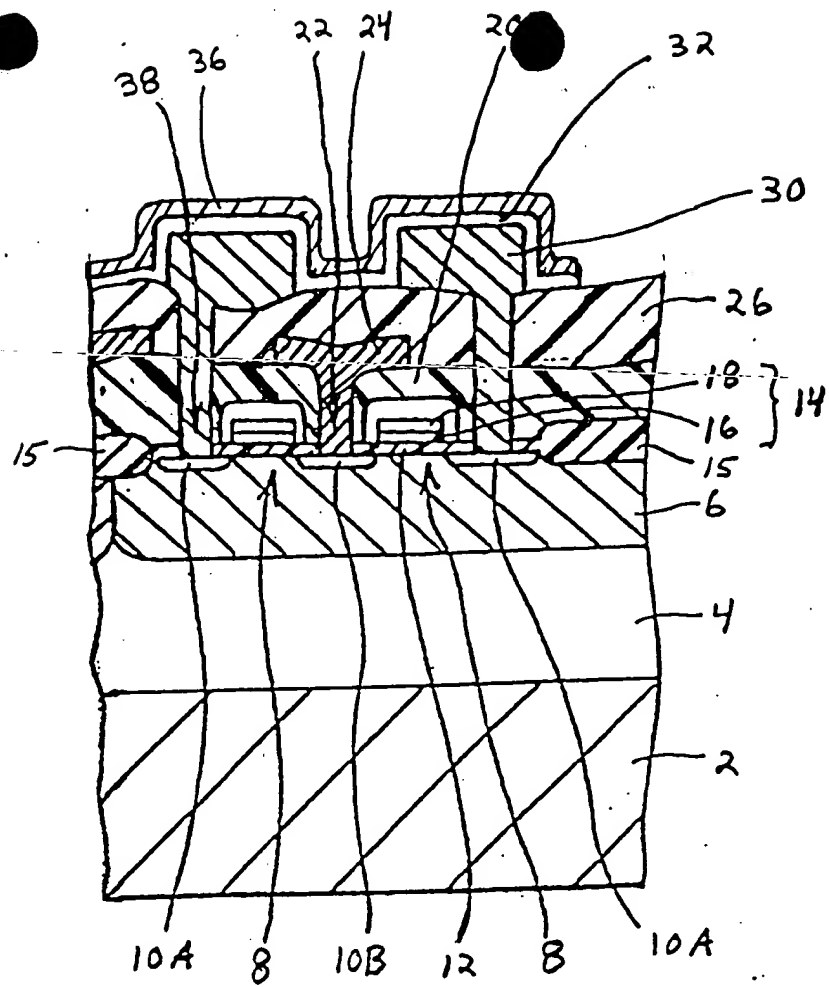


FIG. 7

DEPOSIT DIELECTRIC OR INSULATING FILM



SUBJECT THE INSULATING FILM TO A HEAT TREATMENT IN AN AMBIENT COMPRISING A STABILIZING GAS INCLUDING A GAS SELECTED FROM THE GROUP CONSISTING OF N_2 , O_2 , O_3 , NO, OR N_2O .



SUBJECT THE INSULATING FILM TO A WET OXIDATION IN A RAPID THERMAL PROCESS (RTP) CHAMBER

FIG. 8